

Freescale Semiconductor Application Note

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Addendum to MC68HC908JB16 Technical Data

This addendum provides update and additional information to the *MC68HC908JB16 Technical Data*, Rev. 1.1 (Freescale document number MC68HC908JB16/D).

pertaining to the following:

- MC68HC908JB16
 - Update to V_{REG} LVI trip point
 - 20-pin SOIC package
- MC68HC908JB12

MC68HC908JB16

This section updates data sheet information and introduces the 20-pin SOIC package for the MC68HC908JB16. These updates apply to the 20-pin SOIC only.

V_{REG} LVI Trip Point

Page 318, entry for minimum V_{RFG} LVI trip point voltage has been updated.

From:

| Characteristic | Symbol | Min | Тур | Max | Unit |
|---|-----------|-----|-----|-----|------|
| V _{REG} LVI trip point voltage | V_{LVR} | 2.0 | 2.2 | 2.6 | V |

To:

| V _{REG} LVI trip point voltage | V_{LVR} | 1.9 | 2.2 | 2.6 | V |
|---|-----------|-----|-----|-----|---|





MC68HC908JB16

Output Low Voltage

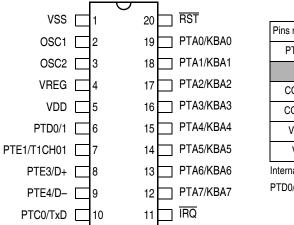
Page 318, entry for maximum V_{OL} has been updated.

From:

| Characteristic | Symbol | Min | Тур | Max | Unit |
|--|-----------------|-----|-----|-----|------|
| Output low voltage (I _{Load} = 25 mA) PTD0-PTD1 in ILDD mode | V _{OL} | _ | _ | 0.5 | V |

To:

20-Pin SOIC Order Number: MC68HC908JB16JDW



| Pins not available on 20-pin package: | | | | |
|---------------------------------------|-------------|------|--|--|
| PTC1/RxD | PTE0/TCLK | PTD2 | | |
| | PTE2/T2CH01 | PTD3 | | |
| CGMXFC1 | CGMXFC2 | PTD4 | | |
| CGMOUT1 | CGMOUT2 | PTD5 | | |
| VREGA0 | VREGA1 | | | |
| VSSA0 | VSSA1 | VDDA | | |

Internal pads are unconnected.

PTD0/1 pin: PTD0 and PTD1 internal pads are bonded together to PTD0/1 pin.

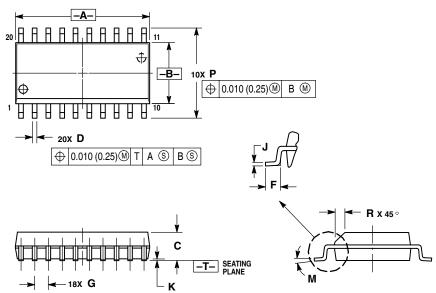
PTD0/1 has a 45 mA sink capability when configured as an output.

Pin direction must be configured such that DDRD0 = DDRD1.

Figure 1. 20-Pin SOIC Pin Assignment

2 Freescale Semiconductor





- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.150
- 4. MAXIMUM MULD PHOTHOSION 0.130 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

| | MILLIN | IETERS | INCHES | |
|-----|--------|--------|-----------|-------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 12.65 | 12.95 | 0.499 | 0.510 |
| В | 7.40 | 7.60 | 0.292 | 0.299 |
| C | 2.35 | 2.65 | 0.093 | 0.104 |
| D | 0.35 | 0.49 | 0.014 | 0.019 |
| F | 0.50 | 0.90 | 0.020 | 0.035 |
| G | 1.27 | BSC | 0.050 BSC | |
| J | 0.25 | 0.32 | 0.010 | 0.012 |
| K | 0.10 | 0.25 | 0.004 | 0.009 |
| М | 0 ° | 7 ° | 0 ° | 7° |
| Р | 10.05 | 10.55 | 0.395 | 0.415 |
| R | 0.25 | 0.75 | 0.010 | 0.029 |

Figure 2. 20-Pin SOIC Mechanical Dimensions (Case No. 751D)





MC68HC908JB12

This section introduces the MC68HC908JB12, a derivative of the MC68HC908JB16. The entire MC68HC908JB16 data book, including the updates in this addendum, applies to this device, with exceptions outlined below.

Table 1. Summary of MC68HC908JB12 and MC68HC908JB16 Differences

| | MC68HC908JB12 | MC68HC908JB16 |
|-----------------------------------|--|---|
| FLASH Memory | 12,288 bytes (\$CA00–\$F9FF) | 16,384 bytes (\$BA00–\$F9FF) |
| Dual Clock Generator Module | Not implemented. \$0051–\$0059 unimplemented. | Yes |
| Available Packages ⁽¹⁾ | — 28-pin SOIC 20-pin SOIC | 32-pin LQFP 28-pin SOIC 20-pin SOIC |

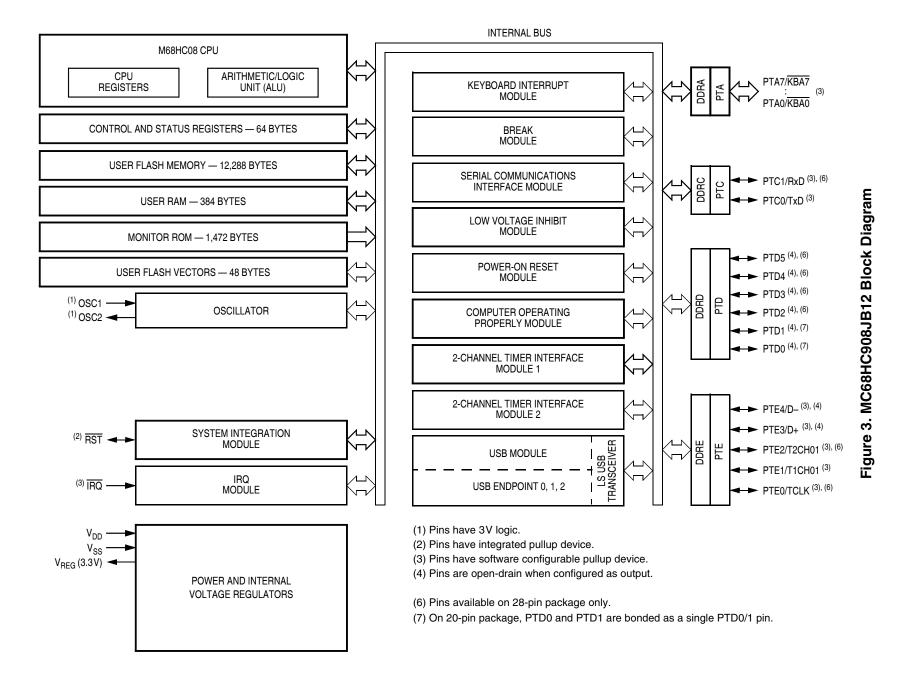
^{1.} The pin assignments are identical for both devices; see data sheet.

MCU Block Diagram Figure 3 shows the structure of the MC68HC908JB12.

Memory Map Figure 4 shows the memory map of the MC68HC908JB12.

Dual Clock Generator Module The dual 27-MHz clock generator module on the MC68HC908JB16 is not designed in the MC68HC908JB12, hence, register locations from \$0051 to \$0059 are unimplemented. Information in the data book relating to the CGM do not apply to the MC68HC908JB12.







MC68HC908JB12

| , | |
|--------------|--|
| \$0000 | I/O Registers |
| ↓ \$007F | 128 Bytes |
| \$0080 | |
| \downarrow | RAM 384 Bytes |
| \$01FF | 304 Bytes |
| \$0200 | Unimplemented |
| \$C9FF | 51,200 Bytes |
| \$CA00 | FLACUL Marrays |
| ↓ | FLASH Memory 12,288 Bytes |
| \$F9FF | , , |
| \$FA00 | Monitor ROM 1 |
| \$FDFF | 1,024 Bytes |
| \$FE00 | SIM Break Status Register (SBSR) |
| \$FE01 | SIM Reset Status Register (SRSR) |
| \$FE02 | Reserved |
| \$FE03 | SIM Break Flag Control Register (SBFCR) |
| \$FE04 | Interrupt Status Register 1 (INT1) |
| \$FE05 | Interrupt Status Register 2 (INT2) |
| \$FE06 | Reserved |
| \$FE07 | Reserved |
| \$FE08 | FLASH Control Register (FLCR) |
| \$FE09 | FLASH Block Protect Register (FLBPR) |
| \$FE0A | Reserved |
| \$FE0B | Reserved |
| \$FE0C | Break Address Register High (BRKH) |
| \$FE0D | Break Address Register Low (BRKL) |
| \$FE0E | Break Status and Control Register (BRKSCR) |
| \$FE0F | Reserved |
| \$FE10 | Monitor ROM 2 |
| ↓ \$FFCF | 448 Bytes |
| \$FFD0 | |
| ψι 1 D0 ↓ | FLASH Vectors |
| \$FFFF | 48 Bytes |
| | |

Figure 4. MC68HC908JB12 Memory Map

6 Freescale Semiconductor



Pullup on PTE3/D+ and PTE4/D- Pins

On the MC68HC908JB12, control over the pullup devices on PTE3/D+ and PTE4/D- pins are shown in **Table 2**.

Table 2. Pullup Control on PTE3/D+ and PTE4/D- Pins

| PULLEN (\$001A) | USBEN (\$0038) | PTExP (\$001D) | PTE4IE (\$001C) | PTE3/D+ pin | PTE4/D- pin |
|--------------------|-------------------|-------------------|--------------------|--|---|
| 0 | 0 | 0 | 0 | _ | _ |
| 0 | 0 | 1 | 0 | 5 k Ω pullup to V _{DD} | 5 k Ω pullup to V _{DD} |
| 0 | 0 | 0 | 1 | _ | 5 k Ω pullup to V _{DD} ⁽¹⁾ |
| 0 | 0 | 1 | 1 | 5 k Ω pullup to V _{DD} | 5 k Ω pullup to V _{DD} ⁽¹⁾ |
| 0 | 1 | Х | Х | _ | _ |
| 1 | 1 | Х | Х | _ | 1.5k Ω pullup to V _{REG} |
| 1 | 0 | Х | 0 | _ | 1.5k Ω pullup to V _{REG} |
| 1 | 0 | Х | 1 | Do not set this | configuration. |

^{1.} External interrupt function is also enabled on PTE4/D- pin.

Electrical Specifications

Electrical specifications for the MC68HC908JB16 apply to the MC68HC908JB12, except for the USB reset timing:

| Bus State | | Signaling Levels | | |
|-----------|------------------|---|--|--|
| bus State | Transmit Receive | | | |
| Reset | NA | D+ and D- < V_{IL} (max) for \geq 8 μ s (MC68HC908JB16) D+ and D- < V_{IL} (max) for \geq 125 μ s (MC68HC908JB12) | | |

Order Numbers

These are MC order numbers for MC68HC908JB12.

Table 3. MC68HC908JB12 Order Numbers

| MC Order Number | Package | Operating Temperature Range |
|------------------|-------------|--------------------------------|
| MC68HC908JB12JDW | 20-pin SOIC | 0 °C to +70 °C |
| MC68HC908JB12DW | 28-pin SOIC | 0 °C to +70 °C |

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